

## Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All recreations are done with the approval of the OCM.

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceed the OCM data sheet.

## Quality Overview

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-35835
  - Class Q Military
  - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)
  - Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OEM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.

# 74F821

## 10-Bit D-Type Flip-Flop

### General Description

The 74F821 is a 10-bit D-type flip-flop with 3-STATE true outputs arranged in a broadside pinout.

### Features

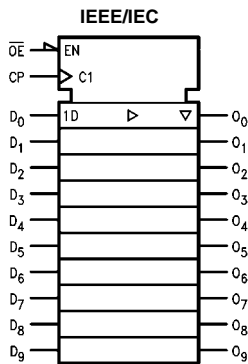
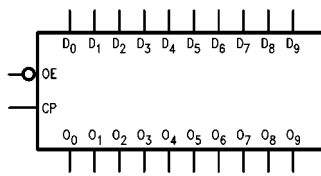
- 3-STATE Outputs

### Ordering Code:

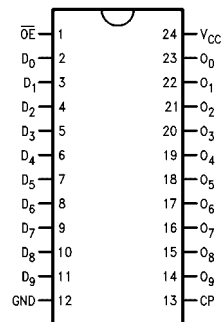
Order Number	Package Number	Package Description
74F821SC	M24B	24-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
74F821SPC	N24C	24-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

### Logic Symbols



### Connection Diagram



## Unit Loading/Fan Out

Pin Names	Description	U.L. HIGH/LOW	Input $I_{IH}/I_{IL}$ Output $I_{OH}/I_{OL}$
$D_0$ – $D_9$	Data Inputs	1.0/1.0	20 $\mu$ A/–0.6 mA
$\overline{OE}$	Output Enable 3-STATE Input	1.0/1.0	20 $\mu$ A/–0.6 mA
CP	Clock Input	1.0/1.0	20 $\mu$ A/–0.6 mA
$O_0$ – $O_9$	3-STATE Outputs	150/40 (33.3)	–3.0 mA/24 mA (20 mA)

## Functional Description

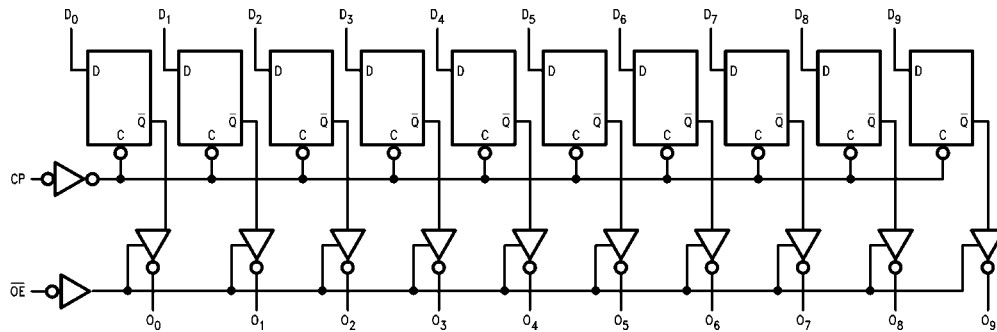
The 74F821 consists of ten D-type edge-triggered flip-flops. This device has 3-STATE true outputs for bus systems organized in a broadside pinning. The buffered Clock (CP) and buffered Output Enable ( $\overline{OE}$ ) are common to all flip-flops. The flip-flops will store the state of their individual D inputs that meet the setup and hold times requirements on the LOW-to-HIGH CP transition. With the  $\overline{OE}$  LOW the content of the flip-flops are available at the outputs. When the  $\overline{OE}$  is HIGH, the outputs go to the high impedance state. Operation of the  $\overline{OE}$  input does not affect the state of the flip-flops.

## Function Table

Inputs			Internal	Output	Function
$\overline{OE}$	CP	D	$\overline{Q}$	O	
H	H	X	NC	Z	Hold
H	L	X	NC	Z	Hold
H	$\nearrow$	L	H	Z	Load
H	$\nearrow$	H	L	Z	Load
L	$\nearrow$	L	H	L	Data Available
L	$\nearrow$	H	L	H	Data Available
L	H	X	NC	NC	No Change in Data
L	L	X	NC	NC	No Change in Data

L = LOW Voltage Level  
H = HIGH Voltage Level  
X = Immaterial  
Z = High Impedance  
 $\nearrow$  = LOW-to-HIGH Transition  
NC = No Change

## Logic Diagram



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

**Absolute Maximum Ratings**(Note 1)

Storage Temperature	-65°C to +150°C
Ambient Temperature under Bias	-55°C to +125°C
Junction Temperature under Bias	-55°C to +150°C
V <sub>CC</sub> Pin Potential to Ground Pin	-0.5V to +7.0V
Input Voltage (Note 2)	-0.5V to +7.0V
Input Current (Note 2)	-30 mA to +5.0 mA

Voltage Applied to Output

in HIGH State (with V<sub>CC</sub> = 0V)Standard Output -0.5V to V<sub>CC</sub>

3-STATE Output -0.5V to +5.5V

Current Applied to Output

in LOW State (Max) twice the rated I<sub>OL</sub> (mA)**Recommended Operating Conditions**

Free Air Ambient Temperature	0°C to +70°C
Supply Voltage	+4.5V to +5.5V

**Note 1:** Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

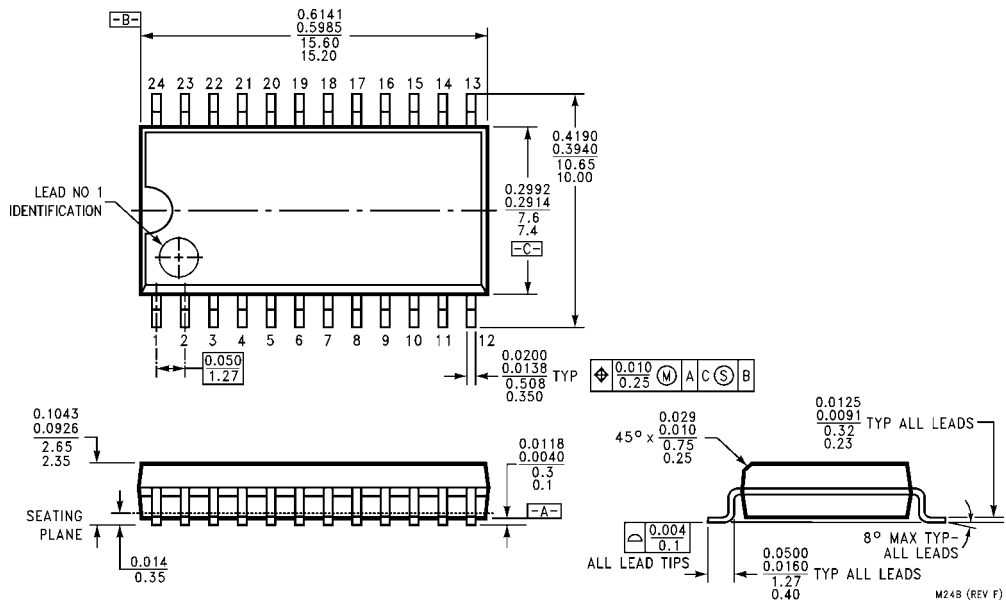
**Note 2:** Either voltage limit or current limit is sufficient to protect inputs.

**DC Electrical Characteristics**

Symbol	Parameter	Min	Typ	Max	Units	V <sub>CC</sub>	Conditions
V <sub>IH</sub>	Input HIGH Voltage	2.0			V		Recognized as a HIGH Signal
V <sub>IL</sub>	Input LOW Voltage			0.8	V		Recognized as a LOW Signal
V <sub>CD</sub>	Input Clamp Diode Voltage			-1.2	V	Min	I <sub>IN</sub> = -18 mA
V <sub>OH</sub>	Output HIGH Voltage	10% V <sub>CC</sub>	2.5		V	Min	I <sub>OH</sub> = -1 mA
		10% V <sub>CC</sub>	2.4	I <sub>OH</sub> = -3 mA			
		5% V <sub>CC</sub>	2.7	I <sub>OH</sub> = -1 mA			
		5% V <sub>CC</sub>	2.7	I <sub>OH</sub> = -3 mA			
V <sub>OL</sub>	Output LOW Voltage			0.5	V	Min	I <sub>OL</sub> = 24 mA
I <sub>IH</sub>	Input HIGH Current			5.0	μA	Max	V <sub>IN</sub> = 2.7V
I <sub>BV1</sub>	Input HIGH Current Breakdown Test			7.0	μA	Max	V <sub>IN</sub> = 7.0V
I <sub>CEx</sub>	Output HIGH Leakage Current			50	μA	Max	V <sub>OUT</sub> = V <sub>CC</sub>
V <sub>ID</sub>	Input Leakage Test	4.75			V	0.0	I <sub>ID</sub> = 1.9 μA, All Other Pins Grounded
I <sub>OD</sub>	Output Leakage Circuit Current			3.75	μA	0.0	V <sub>IOD</sub> = 150 mV All Other Pins Grounded
I <sub>IL</sub>	Input LOW Current			-0.6	mA	Max	V <sub>IN</sub> = 0.5V
I <sub>OZH</sub>	Output Leakage Current			50	μA	Max	V <sub>OUT</sub> = 2.7V
I <sub>OZL</sub>	Output Leakage Current			-50	μA	Max	V <sub>OUT</sub> = 0.5V
I <sub>OS</sub>	Output Short-Circuit Current	-60		-150	mA	Max	V <sub>OUT</sub> = 0V
I <sub>CCZ</sub>	Power Supply Current		78	100	mA	Max	V <sub>O</sub> = HIGH Z

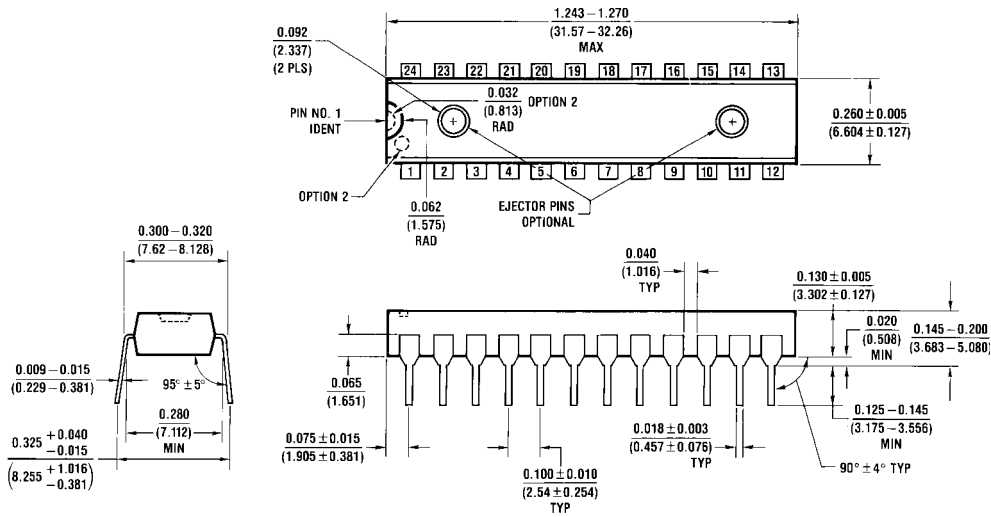
AC Electrical Characteristics									
Symbol	Parameter	$T_A = +25^\circ\text{C}$ $V_{CC} = +5.0\text{V}$ $C_L = 50\text{ pF}$			$T_A = -55^\circ\text{C to } +125^\circ\text{C}$ $V_{CC} = +5.0\text{V}$ $C_L = 50\text{ pF}$		$T_A = 0^\circ\text{C to } +70^\circ\text{C}$ $V_{CC} = +5.0\text{V}$ $C_L = 50\text{ pF}$		Units
		Min	Typ	Max	Min	Max	Min	Max	
$f_{MAX}$	Maximum Clock Frequency	100	150		60		70		MHz
$t_{PLH}$	Propagation Delay	2.0	6.4	9.5	2.0	10.5	2.0	10.5	ns
$t_{PHL}$	CP to $O_n$	2.0	6.2	9.5	2.0	10.5	2.0	10.5	
$t_{PZH}$	Output Enable Time	2.0	5.8	10.5	2.0	13.0	2.0	11.5	ns
$t_{PZL}$	$\overline{OE}$ to $O_n$	2.0	6.3	10.5	2.0	13.0	2.0	11.5	
$t_{PHZ}$	Output Disable Time	1.5	3.4	7.0	1.0	7.5	1.5	7.5	
$t_{PLZ}$	$\overline{OE}$ to $O_n$	1.5	3.5	7.0	1.0	7.5	1.5	7.5	
AC Operating Requirements									
Symbol	Parameter	$T_A = +25^\circ\text{C}$ $V_{CC} = +5.0\text{V}$		$T_A = -55^\circ\text{C to } +125^\circ\text{C}$ $V_{CC} = +5.0\text{V}$		$T_A = 0^\circ\text{C to } +70^\circ\text{C}$ $V_{CC} = +5.0\text{V}$		Units	
		Min	Max	Min	Max	Min	Max		
$t_S(H)$	Setup Time, HIGH or LOW	2.5		4.0		3.0		ns	
$t_S(L)$	$D_n$ to CP	2.5		4.0		3.0			
$t_H(H)$	Hold Time, HIGH or LOW	2.5		2.5		2.5		ns	
$t_H(L)$	$D_n$ to CP	2.5		2.5		2.5			
$t_W(H)$	CP Pulse Width	5.0		6.0		6.0		ns	
$t_W(L)$	HIGH or LOW	5.0		6.0		6.0			

**Physical Dimensions** inches (millimeters) unless otherwise noted



**24-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide  
Package Number M24B**

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



**24-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide Package Number N24C**

N24C (REV F)

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